

Finetech announces FINEPLACER® pico 2 purchase by AmTECH Microelectronics



Finetech, a leading provider of precision die-bonders, announces the purchase of the FINEPLACER[®] pico 2 by *AmTECH Microelectronics*, a Silicon Valley provider of advanced microelectronics assembly and packaging services.

The purchase of the FINEPLACER® pico 2 will advance AmTECH's flip chip bonding and precision die bonding manufacturing services. Designed to deliver high placement accuracy for an array of processes: flip chip bonding, precision die bonding, wafer level packaging, 2.5D and 3D IC stacking, chip-on-board (COB), chip-on-flex (COF), chip-on-glass (COG); in addition to a wide range of other assembly technologies.

The new FINEPLACER® pico 2 system delivers several features that will further benefit AmTECH's customers seeking flip chip and die bonding with precision placement accuracy requirements in optical, medical/ biotech, defense/ aerospace, automotive/ LiDAR, RF/ microwave/ mmWave and other market applications. The FINEPLACER® pico 2 supports all typical bonding technologies such as soldering/ eutectic/ sintering die bond, adhesive bonding, flip chip thermocompression and ultrasonic bonding; as well as process forming gas, epoxy dispensing and UV curing.

Combining micron placement accuracy with a 350mm x 155mm large work area, component sizes up to 100mm x 100mm and a wide range of controlled bonding forces up to 500N; the FINEPLACER[®] pico 2 system features a modular design for valuable flexibility.

"I am so pleased that AmTECH has chosen our technology to deliver the flexibility needed in high accuracy bonding applications for a very diverse customer base. Whether it is heterogeneous integrated assemblies or traditional single die to substrate bonding, the pico 2 will address them all. We look forward to supporting AmTECH in meeting their customers' challenges." stated Neil O'Brien, General Manager, with Finetech

"The FINEPLACER® Pico 2 is the perfect addition to our other microelectronics assembly & packaging equipment and extends our extreme placement accuracy and control to the next level," said David Walter Chavez, Operations Manager for AmTECH. "We are excited about the additional capability and capacity we now have available to support our customer's flip chip and die bond high accuracy placement needs."



About AmTECH

AmTECH Microelectronics was established over 30-years ago by a core team of Silicon Valley professionals. The team's roots come from design for manufacturing and process development of Hybrid Circuits, Multi-Chip Modules (MCM), 2.5D & 3D Heterogeneous Assembly, Chip-On-Board (COB), Chip-On-Flex (COF), PCBA and RF Assembly. AmTECH processes include flip chip C4 & Cu Pillar TCB, die bond, wire bonding, ribbon bonding, dispense & encapsulation, and Surface Mount Technology (SMT).

In the early 1990's AmTECH began designing and manufacturing hundreds of these electronic devices, combining multiple materials, components, assembly technologies and manufacturing processes on Rigid & Flex PCB laminates, and ceramic substrates.

Our "hands-on" engineering team, skilled manufacturing technicians and experienced assembly operators solve manufacturing challenges and accelerate time-to-market for each product we assemble. These products require high levels of value-added engineering, laser-focus attention to detail, and state-of-the-art automated equipment.

Assembly Capabilities	Technology Focus
• Flip Chip C4 and Cu Pillar TCB	 Mixed Technology Assembly
• Die Bond: Epoxy, Eutectic, Sintering	 Chip-On-Board, Chip-On-Flex
Wire Bonding and Ribbon Bonding	• 2.5D & 3D Heterogeneous
• Glob Top, Dam & Fill, UV, Underfill	 MEMS, MCM, SiP, Chiplets
• SMT Assembly (RoHS, Non-RoHS)	PCBA, RF, Microwave, mmWave